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Our File No. 9281-4702

Client No. S US02113

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of: )  
Teruyoshi Kubokawa et al. )  
Serial No. To be Assigned )  
Filing Date: Herewith )  
For Solder Joint Structure and Method for )  
Soldering Electronic Components )

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Prior to examination of the above-identified application, please amend the application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks** begin on page 6 of this paper.